

**IN THE SPECIFICATION:**

Please REPLACE the paragraph beginning at page 9, line 28, with the following paragraph:

[0037] As shown, the upper surface of the support limbs 64 are provided at an angle with respect to the processing surface 61. Accordingly, the central hub 63 of the substrate support 66 is at a lower height than the outer end of the support limbs 64. As a consequence, the substrate 65 is supported by the edges of the substrate contacting the support limbs 64, as shown. As a result, the central hub 63 is positioned below the substrate 65 and there is no contact of any part of the central hub 63~~substrate support 66~~ with the underside of the substrate 65.

Please REPLACE the paragraph beginning at page 10, line 1, with the following paragraph:

[0038] In use, the actuator 68 will initially be actuated to move the substrate support 66 into the extended position. The substrate 65 is then placed on the substrate support 66, as shown in Figure 5. The actuator is then operated to cause the substrate support 66 to gently lower into the retracted position. As a result, the substrate 65 is gently lowered onto the processing surface 61, as shown in Figure 4. It will be realised that such operation ensures that the underside of the substrate 65 is protected from damage as there is no contact with the central hub 63~~substrate support 66~~.

Please REPLACE the paragraph beginning at page 11, line 18, with the following paragraph:

[0044] The telescopic movement and use of mechanical advantage allows a compact loading chamber. As can be seen from Figure 26, the substrate mounting 24 and carriage 25

have approximately the same length in the loading direction, and in its retracted position the substrate mounting 24 lies in register with the carriage 25. This provides a particularly compact construction.

Please REPLACE the paragraph beginning at page 15, line 20, with the following paragraph:

[0061] The third modification to the apparatus is the addition of a pressure regulator 200 which is coupled to a pipe 201 which surrounds the shaft 167. The pipe ~~20~~201 is used to allow helium to flow into the aperture 162 under the control of the pressure regulator 200 of the processing surface 161. This is performed to enhance heat transfer between the substrate and the processing surface 161, when the substrate 165 is lowered onto the processing surface.

Please REPLACE the paragraph beginning at page 16, line 27, with the following paragraph:

[0067] Thus, as shown, a thin film processing chamber 360 having a processing surface 361 is provided with an aperture 362. A substrate support 366 is mounted within the aperture, the substrate support including a number of support limbs ~~264~~364 extending radially outwardly from a central hub 363. The central hub 363 is coupled via a shaft 367 to an actuator 368 so as to allow the substrate support 366 to move between retracted and extended positions, as shown for example in previous embodiments.